

TM18N20D

N-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

General Features

$V_{DS}=200V$ $I_D=18A$

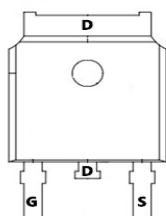
$R_{DS(ON)} = 120 m\Omega$ (typ.) @ $V_{GS}=10V$

100% UIS Tested

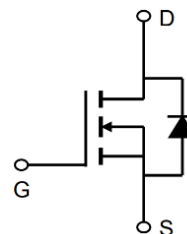
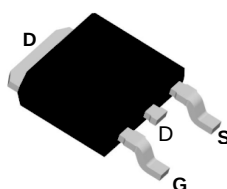
100% R_g Tested



D:TO-252-3L



Marking:18N20



Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	200	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_C=25^\circ C^G$	18	A
	Continuous Drain Current- $T_C=100^\circ C$	13	
E_{AS}	Single Pulse Avalanche Energy	125	mJ
I_{DM}	Drain Current - Pulsed ^C	45	A
I_{AS}	Avalanche Current ^C (L=10mH)	9.5	A
P_D	Power Dissipation, $T_C=25^\circ C^B$	102	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristic

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Steady-State)	0.82	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction to ambient ^A ($t < 10S$)	23	$^\circ C/W$

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Electrical Characteristics: ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Sourtce Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	200	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =200V	---	---	1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 20V, V _{DS} =0A	---	---	± 100	nA
On Characteristics						
V _{GS(th)}	GATE-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	1	2	3	V
R _{DS(ON)}	Drain-Source On Resistance	V _{GS} =10V, I _D =1A	---	120	165	m Ω
		V _{GS} =4.5V, I _D =1A	---	150	180	m Ω
Dynamic Characteristics						
R _g	Gate resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	6.5	----	Ω
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1MHz	---	800	---	pF
C _{oss}	Output Capacitance		---	100	---	
C _{rss}	Reverse Transfer Capacitance		---	60	---	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{GS} =10V ,V _{DS} =100V, R _L =5.5Ω, R _{GEN} =3Ω	---	8	---	ns
t _r	Rise Time		---	10	---	ns
t _{d(off)}	Turn-Off Delay Time		---	30	---	ns
t _f	Fall Time		---	4	---	ns
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =100V, I _D =18A	---	27	40	nC
Q _{gs}	Gate-Source Charge		---	7	---	nC
Q _{gd}	Gate-Drain “Miller” Charge		---	3	---	nC
Drain-Source Diode Characteristics						
V _{SD}	Source-Drain Diode Forward Voltage	I _D =9A	---	---	1.45	V
trr	Body Diode Reverse Recovery Time	IF=18A dI/dt=500A/μs	---	60	80	ns
Qrr	Body Diode Reverse Recovery Charge		---	800	---	nC

Notes:

- A: The value of $R_{\theta JA}$ is measured with the device in a still air environment with $T_A=25^{\circ}\text{C}$.
 B: The power dissipation PD is based on $T_J(\text{MAX})=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
 C: Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX})=150^{\circ}\text{C}$.
 D: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
 E: The static characteristics in Figures 1 to 6 are obtained using $<300\mu s$ pulses, duty cycle 0.5% max.
 F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_J(\text{MAX})=150^{\circ}\text{C}$.
 G: The maximum current rating is limited by bond-wires.

Typical Characteristics: ($T_A=25^\circ\text{C}$ unless otherwise noted)

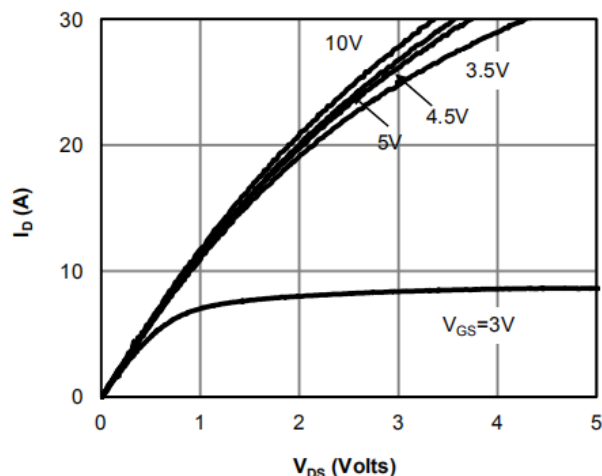


Figure 1: On-Region Characteristics

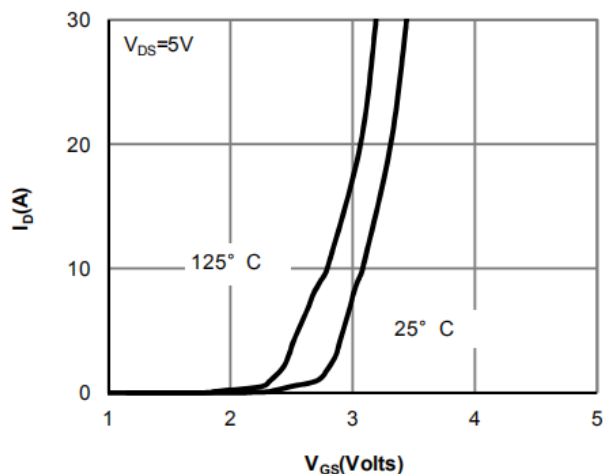


Figure 2: Transfer Characteristics

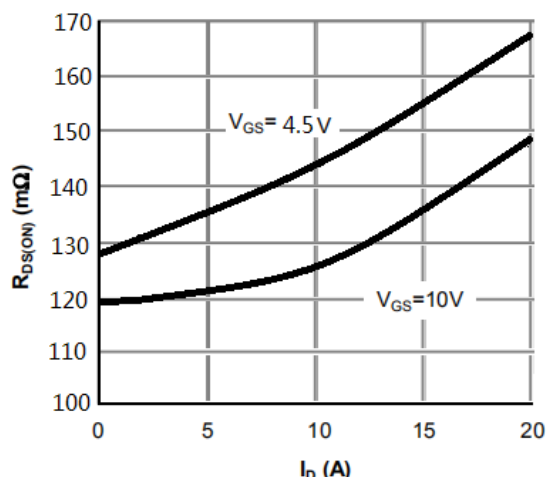


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

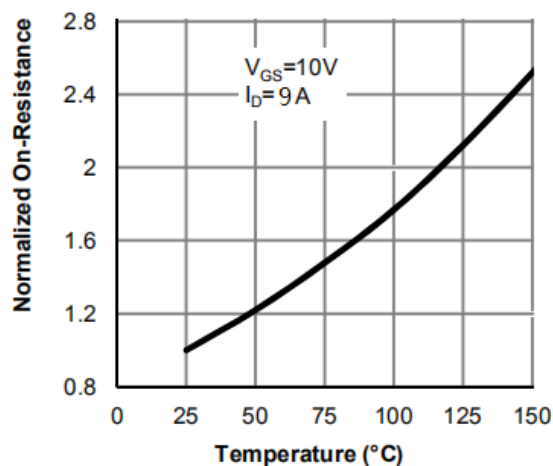


Figure 4: On-Resistance vs. Junction Temperature

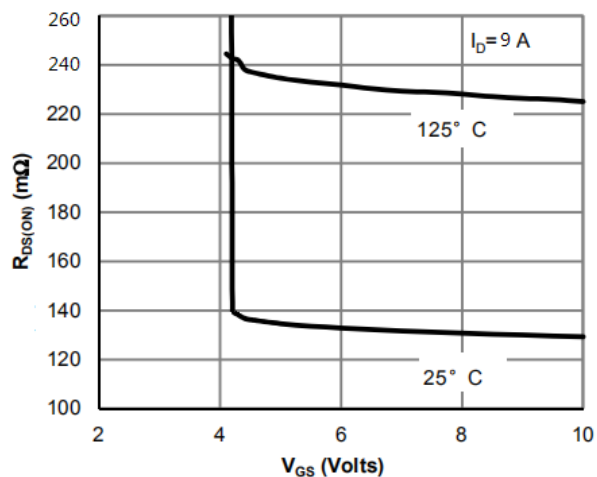


Figure 5: On-Resistance vs. Gate-Source Voltage

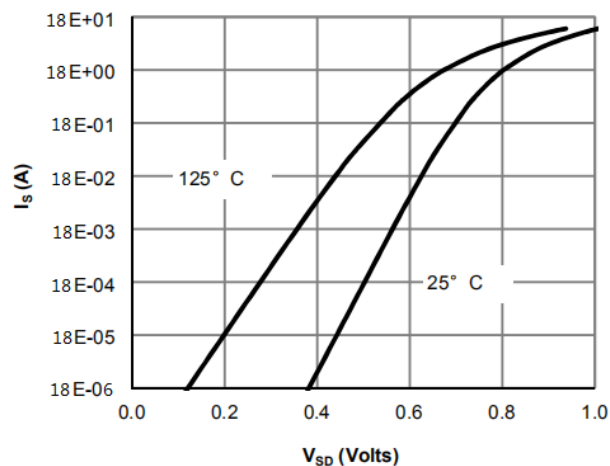


Figure 6: Body-Diode Characteristics

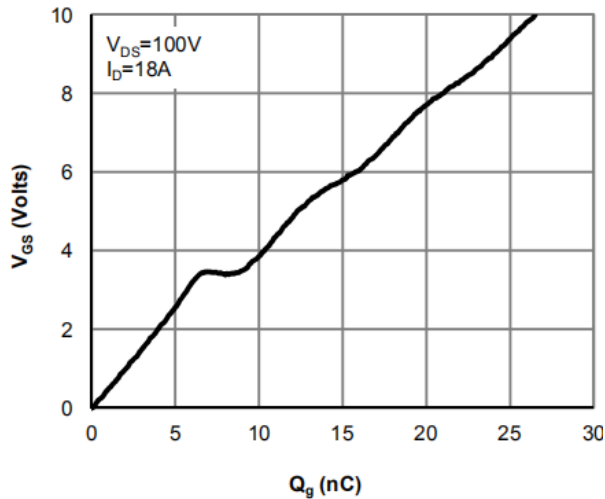


Figure 7: Gate-Charge Characteristics

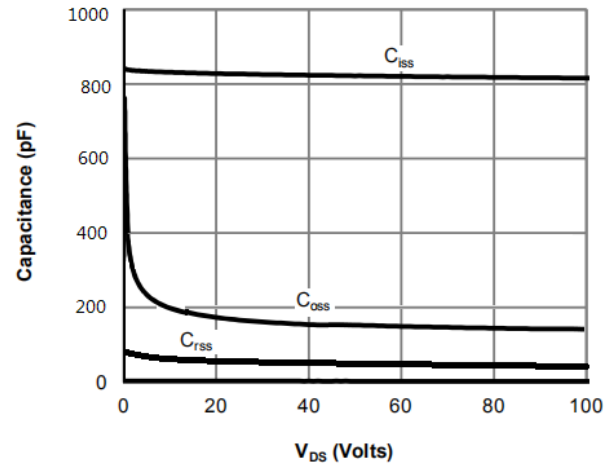


Figure 8: Capacitance Characteristics

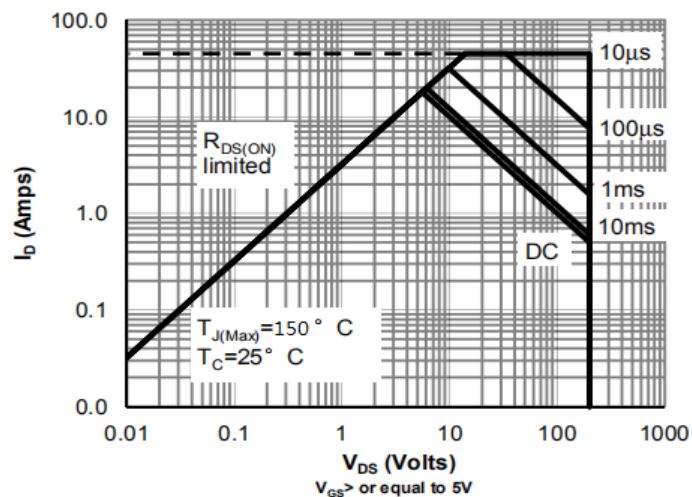


Figure 9: Maximum Forward Biased Safe Operating Area

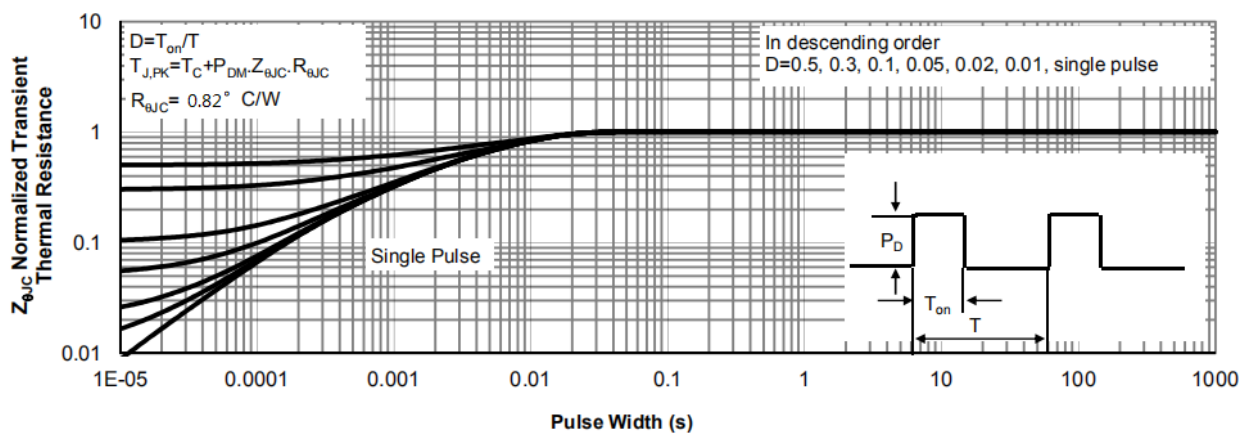
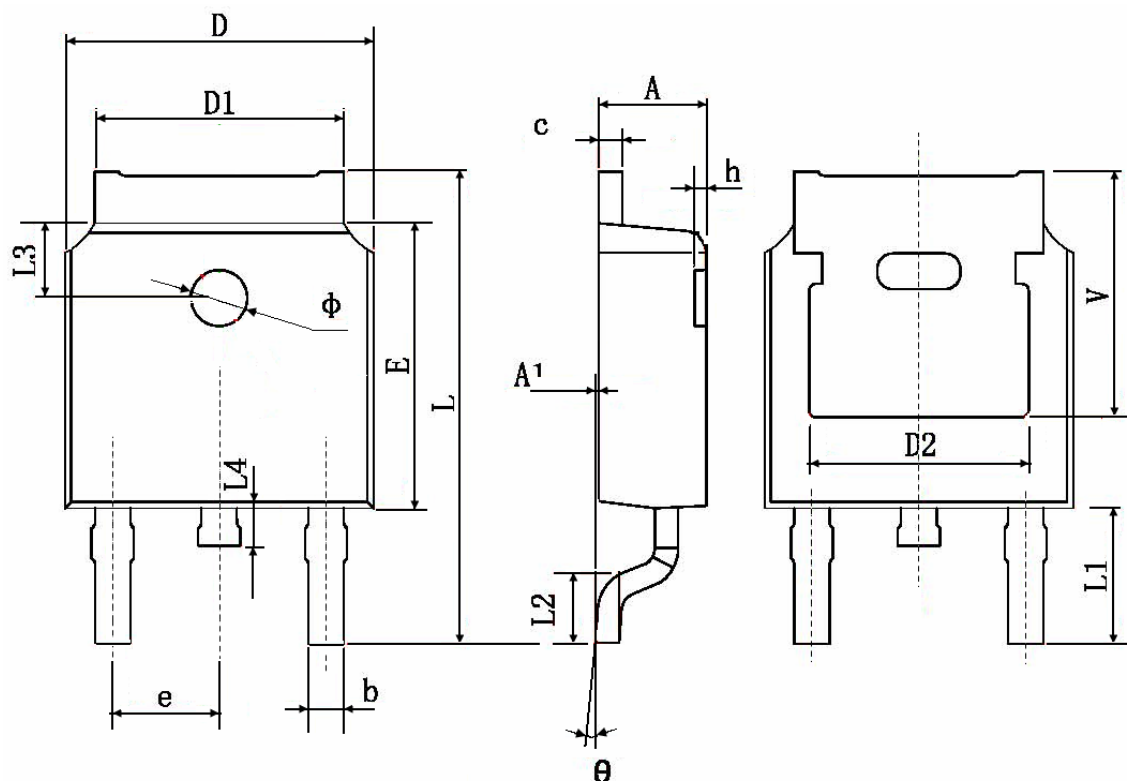


Figure 10: Normalized Maximum Transient Thermal Impedance

Package Mechanical Data: TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	